

**Amendments to the Claims:**

This listing of claims replaces all prior versions, and listings, of claims in this application.

**Listing of Claims:**

1. (Canceled)
2. (Currently Amended) A probe for a probe card characterized in that the same has a structure where either nickel plating or nickel alloy plating is applied to the surface of a core material made of palladium alloy, followed by a wire drawing operation resulting in a wire cross-sectional area reduction of about 70-75%. ~~and then a wire drawing operation with a wire drawing die is performed.~~
3. (Canceled)
4. (Previously presented) The probe for a probe card according to claim 2 characterized in that a gold plating is further applied to the upper-most surface of said probe after said wire drawing operation is performed.
5. (Previously presented) The probe for a probe card according to claim 2, wherein the probe can be applied for performing an inspection of an IC chip having an inter-electrode pitch size of 100  $\mu\text{m}$ .

6. (Previously presented) The probe for a probe card according to claim 2, wherein the probe is 65  $\mu\text{m}$  in diameter.

7. (Previously presented) The probe for a probe card according to claim 6, whereby positional displacement in respect to the IC chip electrode is minimized.

8. (Previously presented) The probe for a probe card according to claim 2, wherein thickness of the nickel plating or nickel alloy plating is 3 – 15  $\mu\text{m}$ .

9. (Previously presented) The probe for a probe card according to claim 4, wherein thickness of the gold plating is about 0.2 – 1.0  $\mu\text{m}$ .

10. (Currently Amended) A probe for a probe card characterized in that the same has a structure where either nickel plating or nickel alloy plating is applied to the surface of a core material made of beryllium copper alloy and then a wire drawing operation with a wire drawing die is performed, followed by a wire drawing operation resulting in a wire cross-sectional area reduction of about 70-75%.

11. (Previously presented) The probe for a probe card according to claim 10, wherein the probe can be applied for performing an inspection of an IC chip having an inter-electrode pitch size of 100  $\mu\text{m}$ .

12. (Previously presented) The probe for a probe card according to claim 10, wherein the probe is 65  $\mu\text{m}$  in diameter.

13. (Previously presented) The probe for a probe card according to claim 10, whereby positional displacement in respect to the IC chip electrode is minimized.

14. (Previously presented) The probe for a probe card according to claim 10, wherein thickness of the nickel plating or nickel alloy plating is 3 – 15  $\mu\text{m}$ .

15. (Previously presented) The probe for a probe card according to claim 10 characterized in that a gold plating is further applied to the upper-most surface of said probe after said wire drawing operation is performed.

16. (Previously presented) The probe for a probe card according to claim 15, wherein thickness of the gold plating is about 0.2 – 1.0  $\mu\text{m}$ .

17. (Cancelled)

18. (New) A probe for a probe card characterized in that the same has a structure where either nickel plating or nickel alloy plating is applied to the surface of a core material made of a metal alloy and then a wire drawing operation with a wire drawing die is performed,

wherein the probe sustains a substantially higher contact force as compared to a probe made of metal alloy wire that is not subject to the wire drawing operation.

19. (New) The probe for a probe card of claim 18, wherein the metal alloy comprises one of: a palladium alloy and a copper beryllium alloy.

20. (New) The probe for a probe card of claim 18, wherein the probe has a substantially superior spring characteristic and hardness as compared to a probe made of metal alloy wire that is not subject to the wire drawing operation.